

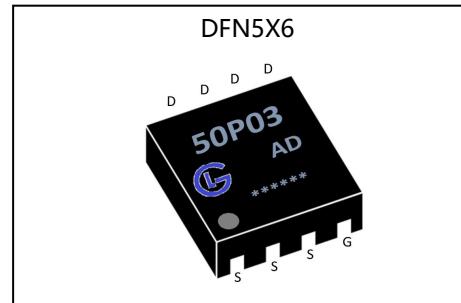
### General Description

The GL50P03AD uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. The package form is DFN-5×6, which accords with the RoHS standard.

$V_{DSS}$	-30	V
$I_D$	-50	A
$P_D$	60	W
$R_{DS(ON)}$ TYPE	6	$m\Omega$

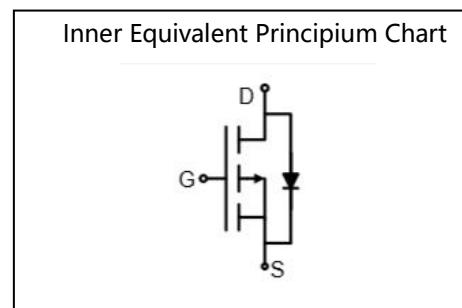
### Features

- Fast Switching
- Low Gate Charge and  $R_{DS(on)}$
- Low Reverse transfer capacitances



### Applications

- Battery switching application
- Hard switched and high frequency circuits
- Power management



### Absolute Maximum Ratings (TA = 25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-to-Source Voltage	-30	V
$I_D$	Continuous Drain Current $T_C = 25^\circ C$	-50	A
	Continuous Drain Current $T_C = 70^\circ C$	-40	A
$I_{DM}^{a1}$	Pulsed Drain Current	-200	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$P_D$	Power Dissipation	60	W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	150, -55 to 150	°C
$T_L$	Maximum Temperature for Soldering	300	°C

Caution Stresses greater than those in the "Absolute Maximum Ratings" may cause permanent damage to the device

### Thermal Characteristics

Symbol	Parameter	Typ.	Units
$R_{\theta JC}$	Junction-to-Case	2.1	°C/W



# GL50P03AD

## GL Silicon P-Channel Power MOSFET

**Electrical Characteristics** (T<sub>c</sub>= 25°C unless otherwise specified)

### OFF Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =-250μA	-30	-33	--	V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	--	--	-1	μA
I <sub>GSS(F)</sub>	Gate to Source Forward Leakage	V <sub>GS</sub> =+20V	--	--	100	nA
I <sub>GSS(R)</sub>	Gate to Source Reverse Leakage	V <sub>GS</sub> =-20V	--	--	-100	nA

### ON Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R <sub>DS(ON)1</sub>	Drain-to-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	--	6	9	mΩ
R <sub>DS(ON)</sub>	Drain-to-Source On-Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A	--	10	15	mΩ
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-1.5	-2.0	V

### Dynamic Characteristics

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-15V, I <sub>D</sub> =-10A	--	20	--	S
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	--	3000	--	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =-15V	--	650	--	
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	--	550	--	

### Resistive Switching Characteristics

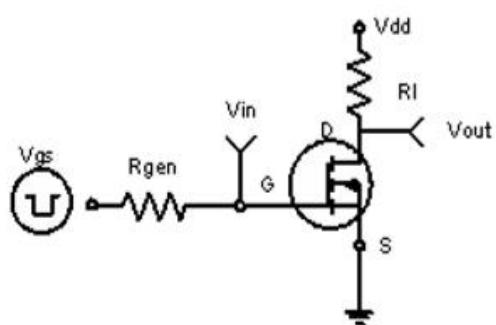
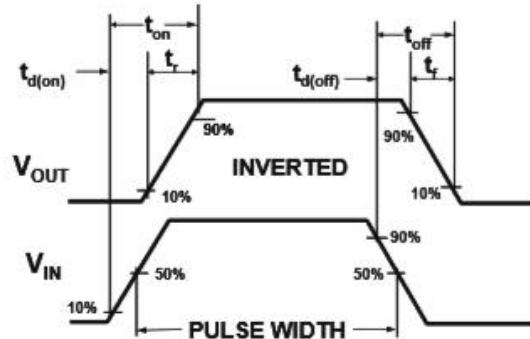
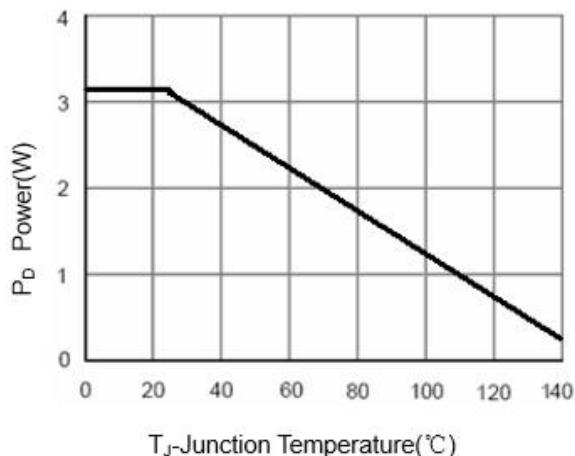
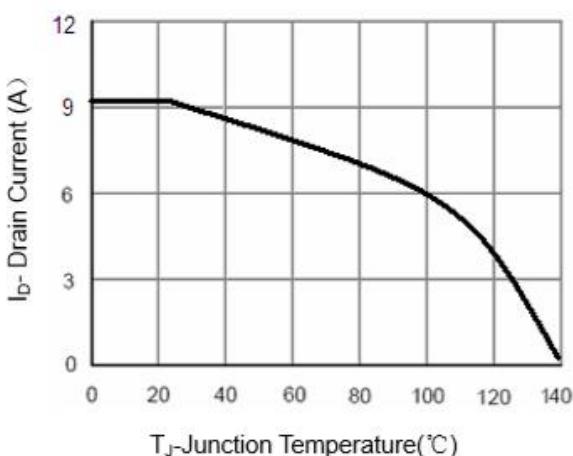
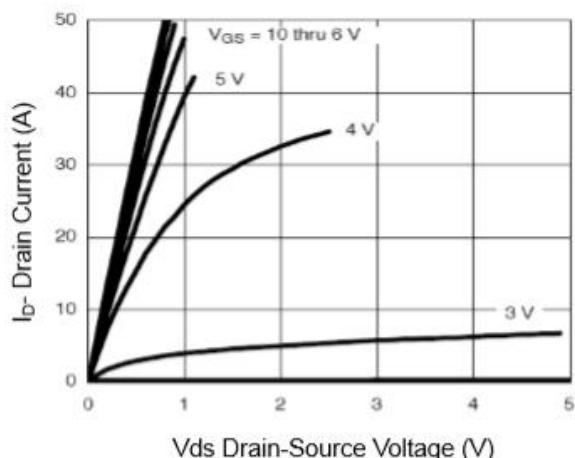
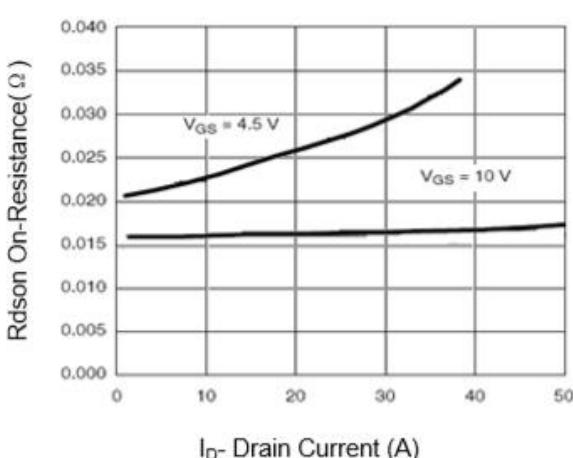
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t <sub>d(ON)</sub>	Turn-on Delay Time		--	10	--	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =-1.0A, V <sub>DS</sub> =-15V	--	15	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time	V <sub>GS</sub> =-10V, R <sub>G</sub> =6.0Ω	--	110	--	
t <sub>f</sub>	Fall Time		--	70	--	
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> =-10A, V <sub>DS</sub> = -15V	--	60	--	nC
Q <sub>gs</sub>	Gate to Source Charge	V <sub>GS</sub> =-10V	--	10.5	--	
Q <sub>gd</sub>	Gate to Drain ( "Miller" ) Charge		--	14.5	--	

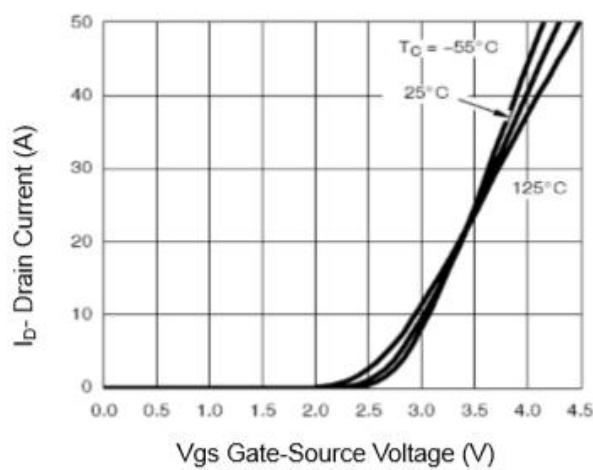
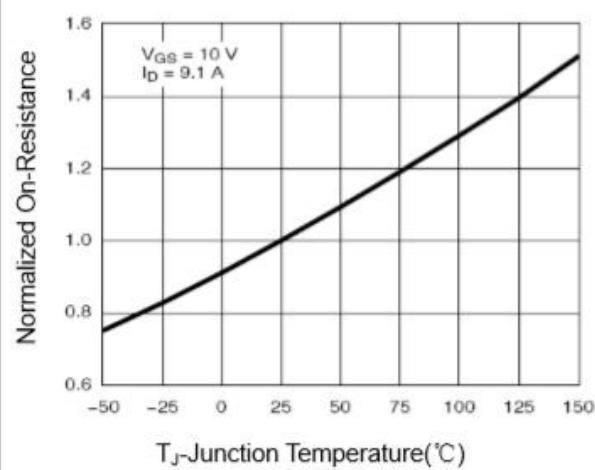
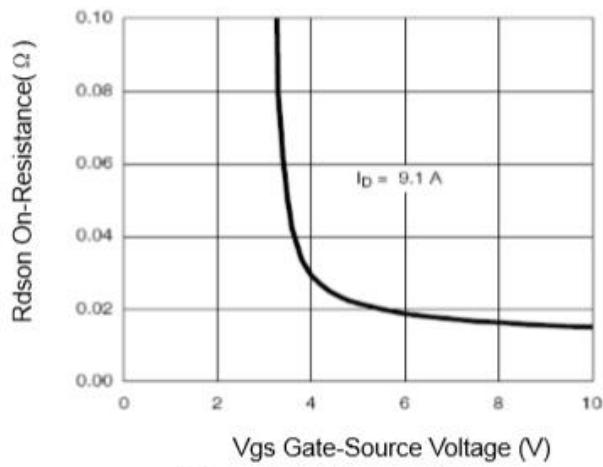
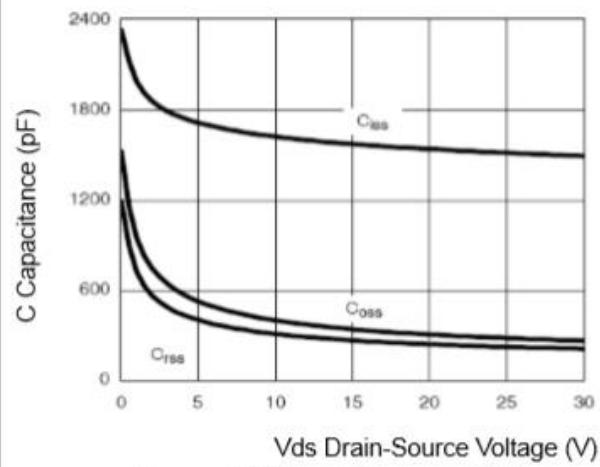
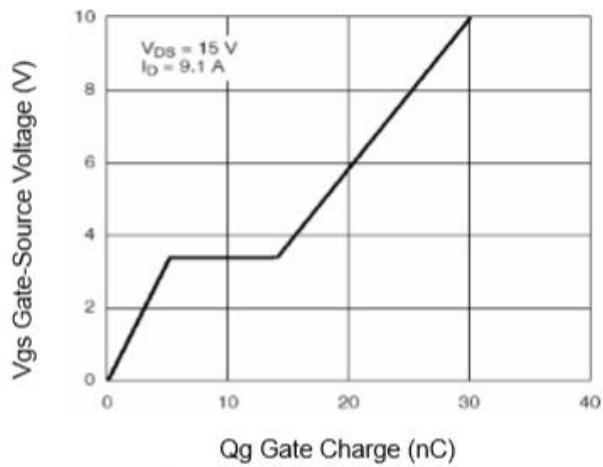
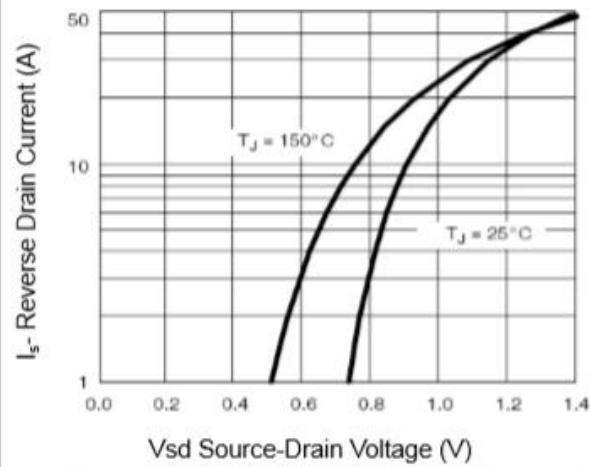
### Source-Drain Diode Characteristics

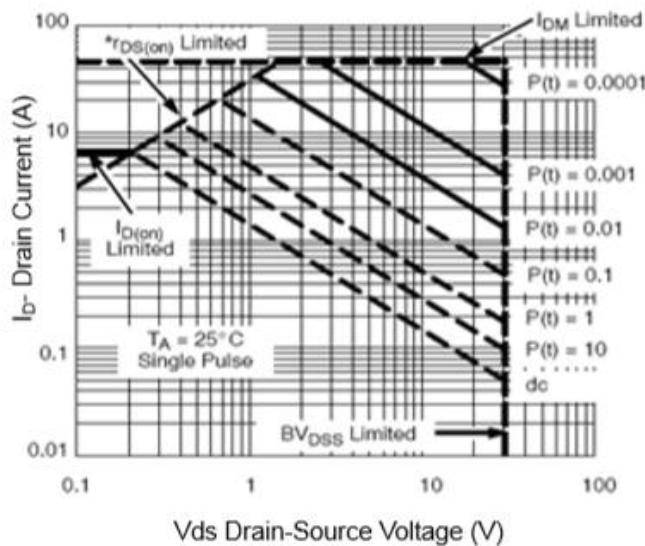
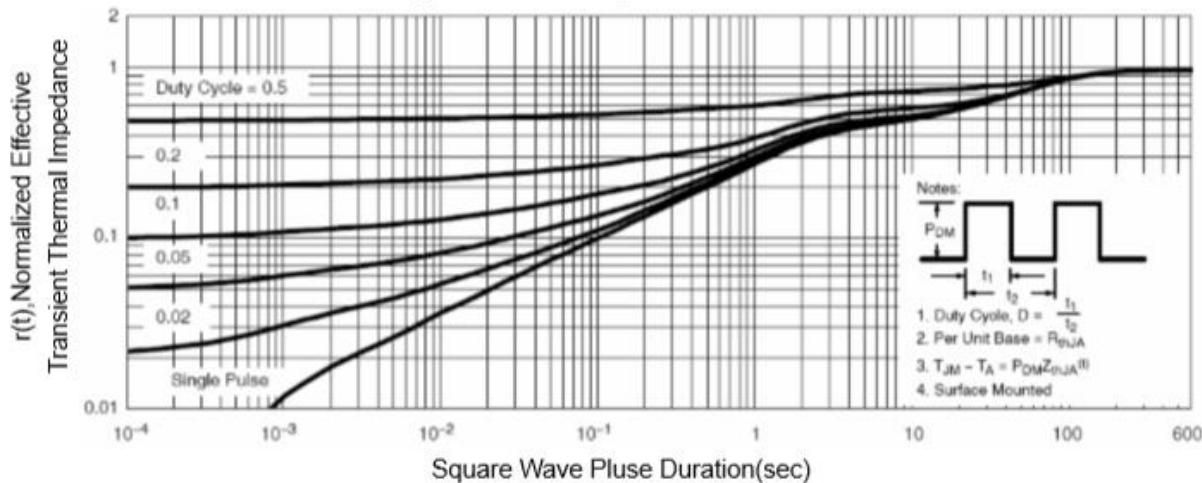
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I <sub>s</sub>	Diode Forward Current		--	--	-50	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>s</sub> =-15A, V <sub>GS</sub> =0V	--	--	-1.5	V

<sup>a1</sup>: Repetitive rating; pulse width limited by maximum junction temperature

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**Characteristics Curves**

**Figure 1:Switching Test Circuit**

**Figure 2:Switching Waveforms**

**Figure 3 Power Dissipation**

**Figure 4 Drain Current**

**Figure 5 Output Characteristics**

**Figure 6 Drain-Source On-Resistance**

***GL Silicon P-Channel Power MOSFET***

**Figure 7 Transfer Characteristics**

**Figure 8 Drain-Source On-Resistance**

**Figure 9  $R_{DS(on)}$  vs  $V_{GS}$** 

**Figure 10 Capacitance vs  $V_{DS}$** 

**Figure 11 Gate Charge**

**Figure 12 Source-Drain Diode Forward**


**Figure 13 Safe Operation Area**

**Figure 14 Normalized Maximum Transient Thermal Impedance**